

## 30V N-Channel Enhancement Mode MOSFET

**VDS= 30V**

RDS(ON), Vgs@ 10V, Ids@ 3.5A <70mΩ

RDS(ON), Vgs@ 4.5V, Ids@ 2.8A <80mΩ

### Features

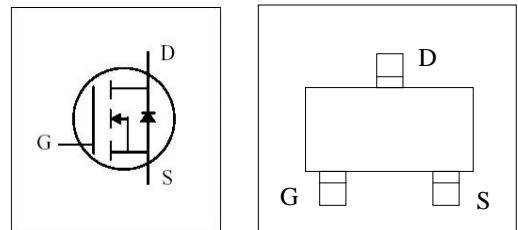
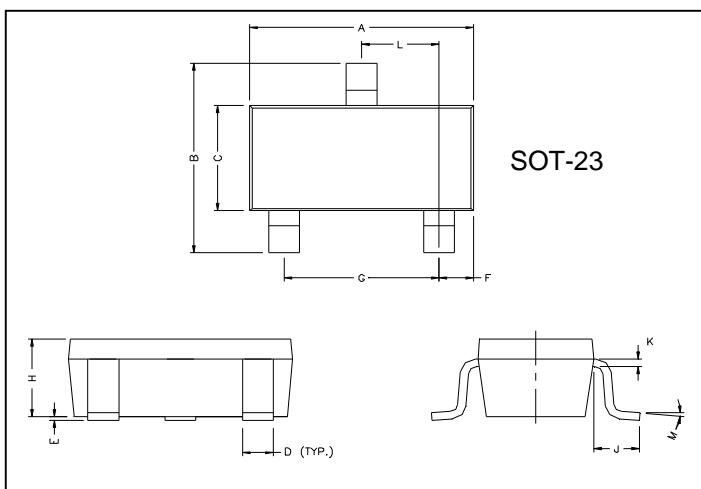
Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

High Power and Current handling capability

Ideal for Li ion battery pack applications

### Package Dimensions



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.80	3.00	G	1.80	2.00
B	2.30	2.50	H	0.90	1.1
C	1.20	1.40	K	0.10	0.20
D	0.30	0.50	J	0.35	0.70
E	0	0.10	L	0.92	0.98
F	0.45	0.55	M	0°	10°

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	±20		
Continuous Drain Current (T <sub>J</sub> = 150°C) <sup>a, b</sup>	I <sub>D</sub>	T <sub>A</sub> = 25°C	3.5	A
		T <sub>A</sub> = 70°C	2.8	
Pulsed Drain Current	I <sub>DM</sub>	16		
Continuous Source Current (Diode Conduction) <sup>a, b</sup>	I <sub>S</sub>	1.25		
Maximum Power Dissipation <sup>a, b</sup>	P <sub>D</sub>	T <sub>A</sub> = 25°C	1.25	W
		T <sub>A</sub> = 70°C	0.80	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C	

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	R <sub>thJA</sub>		100	°C/W
		t ≤ 5 sec		
		Steady State	130	

#### Notes

a. Surface Mounted on FR4 Board.

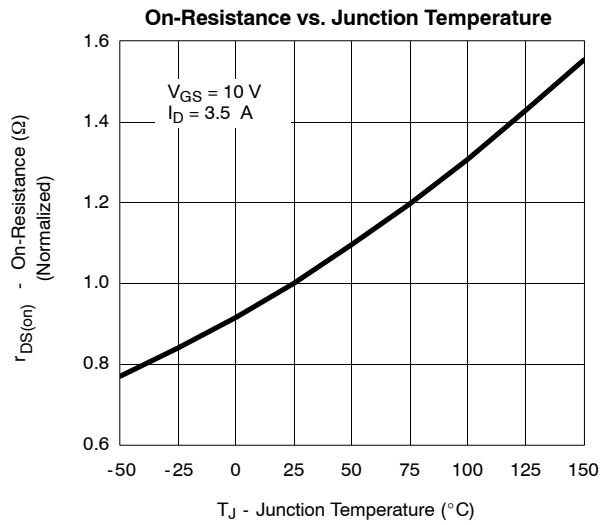
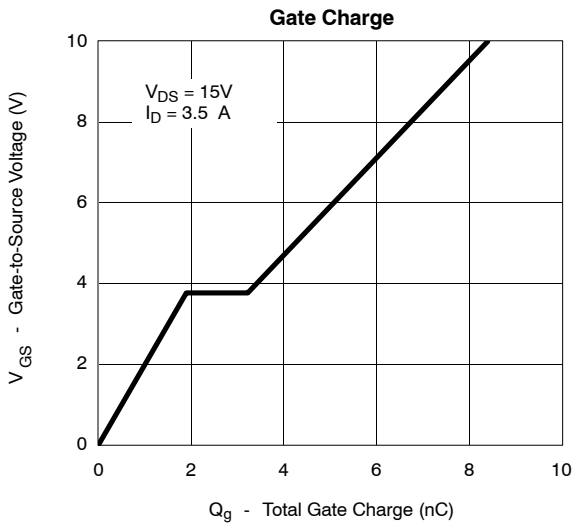
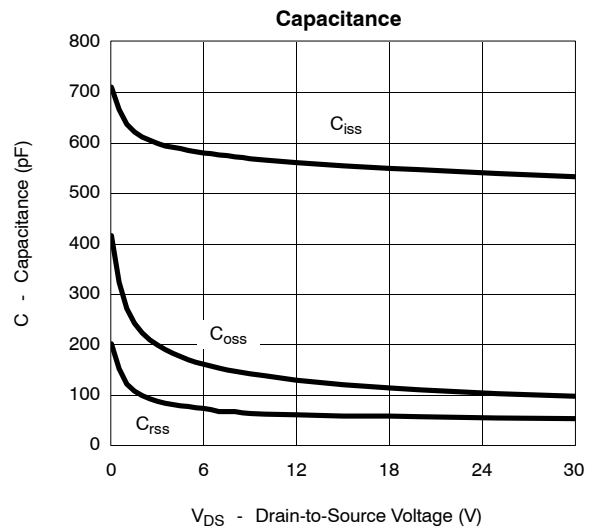
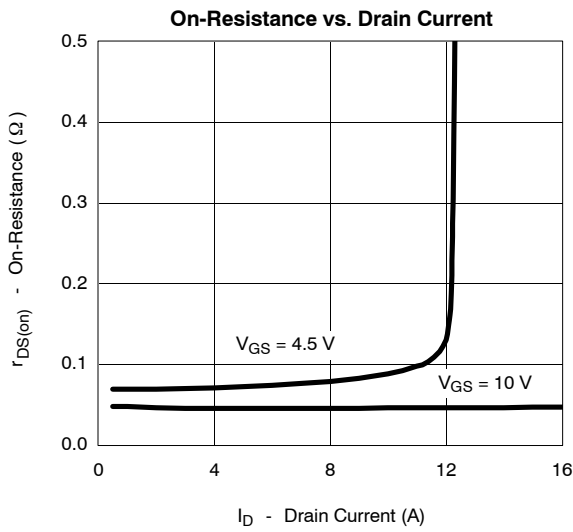
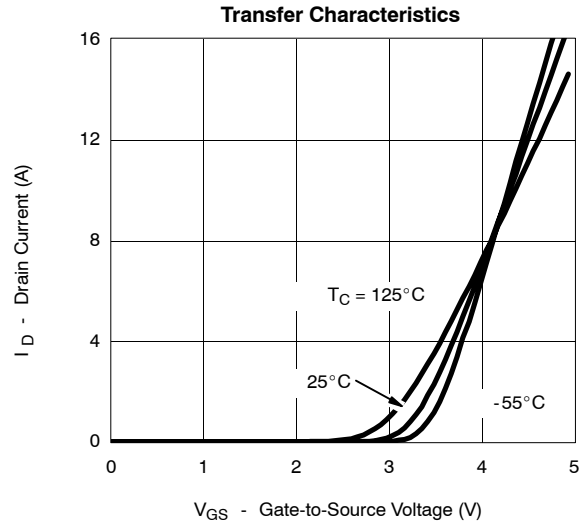
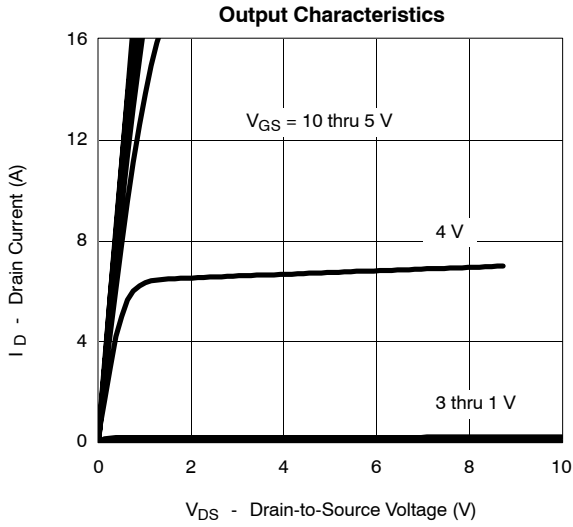
b. t ≤ 5 sec.

SPECIFICATIONS ( $T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{DS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1			
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$			0.5	$\mu\text{A}$
		$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}, T_J = 55^\circ\text{C}$			10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \geq 4.5\text{ V}, V_{GS} = 10\text{ V}$	6			A
		$V_{DS} \geq 4.5\text{ V}, V_{GS} = 4.5\text{ V}$	4			
Drain-Source On-State Resistance <sup>a</sup>	$r_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 3.5\text{ A}$		0.046	0.057	$\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 2.8\text{ A}$		0.070	0.094	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 4.5\text{ V}, I_D = 3.5\text{ A}$		6.9		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = 1.25\text{ A}, V_{GS} = 0\text{ V}$		0.8	1.2	V
<b>Dynamic<sup>b</sup></b>						
Gate Charge	$Q_g$	$V_{DS} = 15\text{ V}, V_{GS} = 5\text{ V}, I_D = 3.5\text{ A}$		4.2	7	nC
Total Gate Charge	$Q_{gt}$	$V_{DS} = 15\text{ V}, V_{GS} = 10\text{ V}, I_D = 3.5\text{ A}$		8.5	20	
Gate-Source Charge	$Q_{gs}$			1.9		
Gate-Drain Charge	$Q_{gd}$			1.35		
Gate Resistance	$R_g$		0.5		2.4	$\Omega$
Input Capacitance	$C_{iss}$	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		555		$\mu\text{F}$
Output Capacitance	$C_{oss}$			120		
Reverse Transfer Capacitance	$C_{rss}$			60		
<b>Switching</b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}, R_L = 15\ \Omega$ $I_D \cong 1\text{ A}, V_{GEN} = 10\text{ V}, R_G = 6\ \Omega$		9	20	ns
Rise Time	$t_r$			7.5	18	
Turn-Off Delay Time	$t_{d(off)}$			17	35	
Fall Time	$t_f$			5.2	12	

## Notes

- a. Guaranteed by design, not subject to production testing.  
b. Pulse test; pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**



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